
HM621400H Series

4M High Speed SRAM (4-Mword $\times$ 1-bit)

HITACHI

ADE-203-787D (Z)

Rev. 1.0

Sept. 15, 1998

Description

The HM621400H is a 4-Mbit high speed static RAM organized 4-Mword $\times$ 1-bit. It has realized high speed access time by employing CMOS process (4-transistor + 2-poly resistor memory cell) and high speed circuit designing technology. It is most appropriate for the application which requires high speed and high density memory, such as cache and buffer memory in system. The HM621400H is packaged in 400-mil 32-pin SOJ for high density surface mounting.

Features

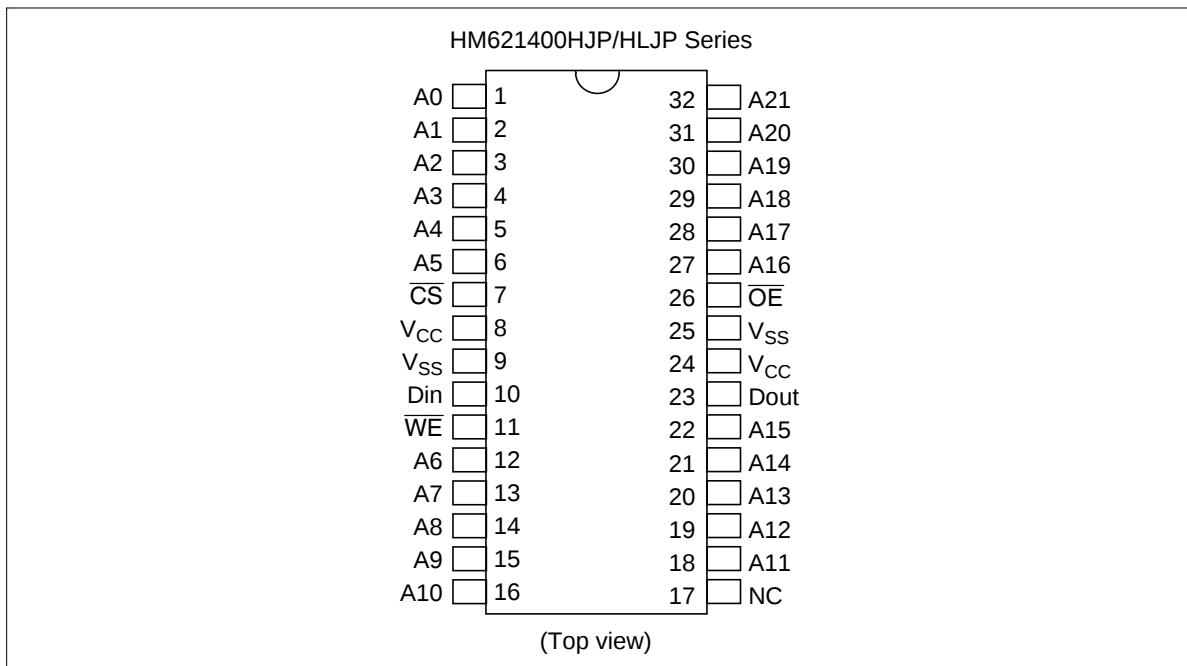
- Single 5.0 V supply : 5.0 V $\pm$ 10 %
- Access time 10/12/15 ns (max)
- Completely static memory
 - No clock or timing strobe required
- Equal access and cycle times
- Directly TTL compatible
 - All inputs and outputs
- Operating current: 200/180/160 mA (max)
- TTL standby current: 70/60/50 mA (max)
- CMOS standby current: 5 mA (max)
 - : 1.2 mA (max) (L-version)
- Data retention current: 0.8 mA (max) (L-version)
- Data retention voltage: 2 V (min) (L-version)
- Center V_{CC} and V_{SS} type pinout

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Ordering Information

Type No.	Access time	Package
HM621400HJP-10	10 ns	400-mil 32-pin plastic SOJ (CP-32DB)
HM621400HJP-12	12 ns	
HM621400HJP-15	15 ns	
HM621400HLJP-10	10 ns	
HM621400HLJP-12	12 ns	
HM621400HLJP-15	15 ns	

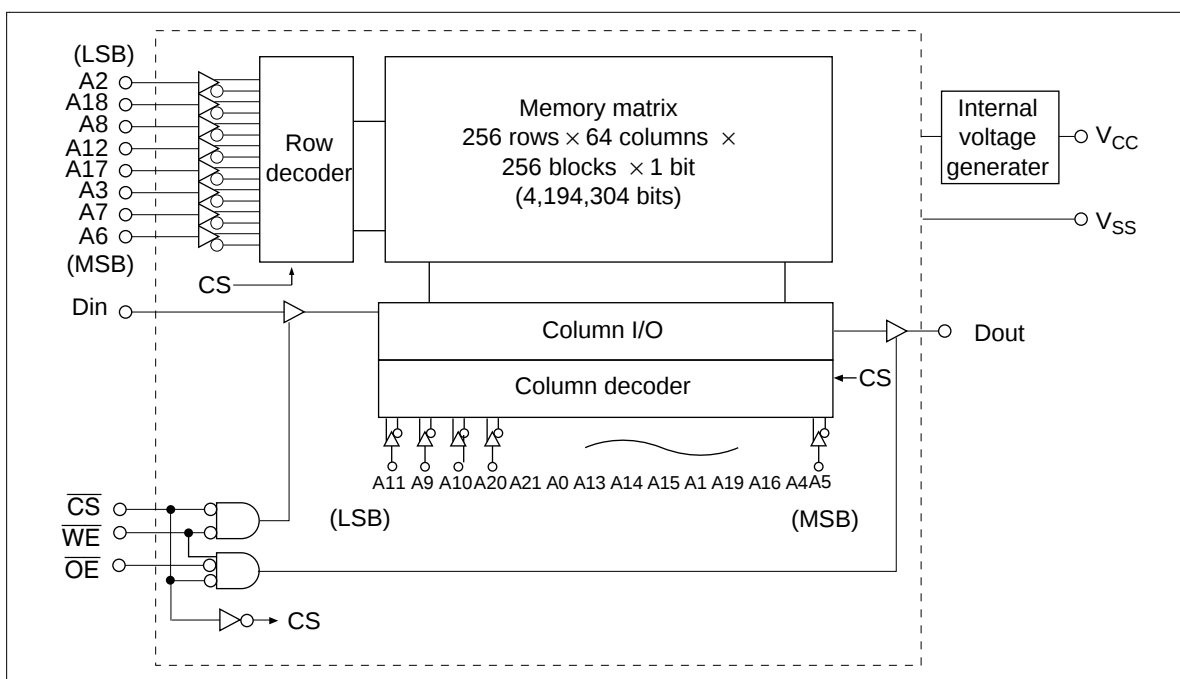
Pin Arrangement



Pin Description

Pin name	Function
A0 to A21	Address input
Din	Data input
Dout	Data output
$\overline{CS}$	Chip select
$\overline{OE}$	Output enable
$\overline{WE}$	Write enable
V_{CC}	Power supply
V_{SS}	Ground
NC	No connection

Block Diagram



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Operation Table

$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	Mode	V_{CC} current	Dout	Ref. cycle
H	×	×	Standby	I_{SB}, I_{SB1}	High-Z	—
L	H	H	Output disable	I_{CC}	High-Z	—
L	L	H	Read	I_{CC}	Dout	Read cycle (1) to (3)
L	H	L	Write	I_{CC}	High-Z	Write cycle (1)
L	L	L	Write	I_{CC}	High-Z	Write cycle (2)

Note: ×: H or L

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Supply voltage relative to V_{SS}	V_{CC}	−0.5 to +7.0	V
Voltage on any pin relative to V_{SS}	V_T	−0.5* ¹ to $V_{CC}+0.5$ * ²	V
Power dissipation	P_T	1.0	W
Operating temperature	T_{opr}	0 to +70	°C
Storage temperature	T_{stg}	−55 to +125	°C
Storage temperature under bias	T_{bias}	−10 to +85	°C

Notes: 1. V_T (min) = −2.0 V for pulse width (under shoot) ≤ 8 ns
 2. V_T (max) = $V_{CC} + 2.0$ V for pulse width (over shoot) ≤ 8 ns

Recommended DC Operating Conditions ($T_a = 0$ to +70°C)

Parameter	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC} * ³	4.5	5.0	5.5	V
	V_{SS} * ⁴	0	0	0	V
Input voltage	V_{IH}	2.2	—	$V_{CC} + 0.5$ * ²	V
	V_{IL}	−0.5* ¹	—	0.8	V

Notes: 1. V_{IL} (min) = −2.0 V for pulse width (under shoot) ≤ 8 ns
 2. V_{IH} (max) = $V_{CC} + 2.0$ V for pulse width (over shoot) ≤ 8 ns
 3. The supply voltage with all V_{CC} pins must be on the same level.
 4. The supply voltage with all V_{SS} pins must be on the same level.

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DC Characteristics (Ta = 0 to +70°C, V_{CC} = 5.0 V ± 10 %, V_{SS} = 0V)

Parameter	Symbol	Min	Typ* ¹	Max	Unit	Test conditions
Input leakage current	I _{LI}	—	—	2	μA	V _{in} = V _{SS} to V _{CC}
Output leakage current	I _{LO}	—	—	2	μA	V _{in} = V _{SS} to V _{CC}
Operation power supply current	10 ns cycle I _{CC}	—	—	200	mA	Min cycle CS = V _{IL} , I _{out} = 0 mA Other inputs = V _{IH} /V _{IL}
	12 ns cycle I _{CC}	—	—	180		
	15 ns cycle I _{CC}	—	—	160		
Standby power supply current	10 ns cycle I _{SB}	—	—	70	mA	Min cycle, CS = V _{IH} , Other inputs = V _{IH} /V _{IL}
	12 ns cycle I _{SB}	—	—	60		
	15 ns cycle I _{SB}	—	—	50		
	I _{SB1}	—	0.1	5	mA	f = 0 MHz V _{CC} ≥ CS ≥ V _{CC} - 0.2 V, (1) 0 V ≤ V _{in} ≤ 0.2 V or (2) V _{CC} ≥ V _{in} ≥ V _{CC} - 0.2 V
		—* ²	0.1* ²	1.2* ²		
Output voltage	V _{OL}	—	—	0.4	V	I _{OL} = 8 mA
	V _{OH}	2.4	—	—	V	I _{OH} = -4 mA

Notes: 1. Typical values are at V_{CC} = 5.0 V, Ta = +25°C and not guaranteed.
2. This characteristics is guaranteed only for L-version.

Capacitance (Ta = +25°C, f = 1.0 MHz)

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions
Input capacitance* ¹	C _{in}	—	—	6	pF	V _{in} = 0 V
	C _{DIN}	—	—	8	pF	V _{DIN} = 0 V
Input/output capacitance* ¹	C _{DOUT}	—	—	8	pF	V _{DOUT} = 0 V

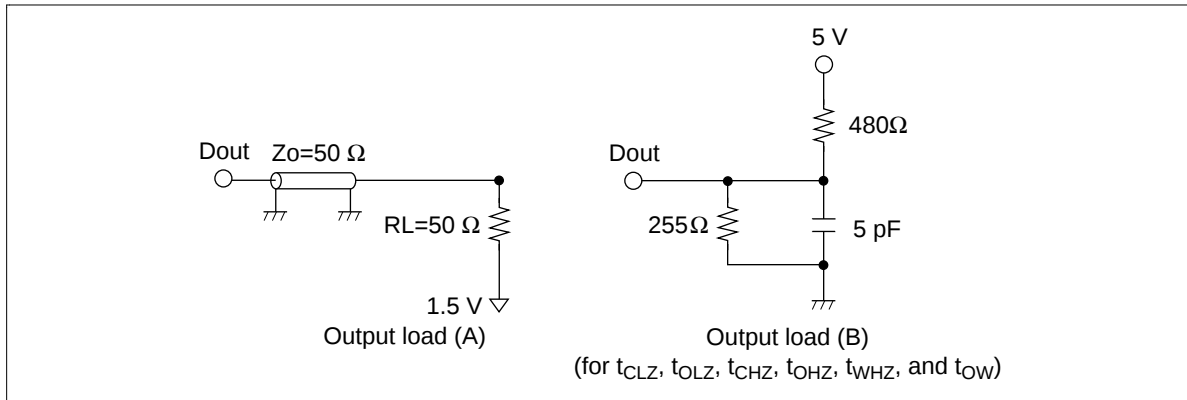
Note: 1. This parameter is sampled and not 100% tested.

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AC Characteristics ($T_a = 0$ to $+70^\circ\text{C}$, $V_{CC} = 5.0\text{ V} \pm 10\%$, unless otherwise noted.)

Test Conditions

- Input pulse levels: 3.0 V/0.0 V
- Input rise and fall time: 3 ns
- Input and output timing reference levels: 1.5 V
- Output load: See figures (Including scope and jig)



Read Cycle

		HM621400H							
		-10		-12		-15			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Read cycle time	t_{RC}	10	—	12	—	15	—	ns	
Address access time	t_{AA}	—	10	—	12	—	15	ns	
Chip select access time	t_{ACS}	—	10	—	12	—	15	ns	
Output enable to output valid	t_{OE}	—	5	—	6	—	7	ns	
Output hold from address change	t_{OH}	3	—	3	—	3	—	ns	
Chip select to output in low-Z	t_{CLZ}	3	—	3	—	3	—	ns	1
Output enable to output in low-Z	t_{OLZ}	0	—	0	—	0	—	ns	1
Chip deselect to output in high-Z	t_{CHZ}	—	5	—	6	—	7	ns	1
Output disable to output in high-Z	t_{OHZ}	—	5	—	6	—	7	ns	1

Write Cycle

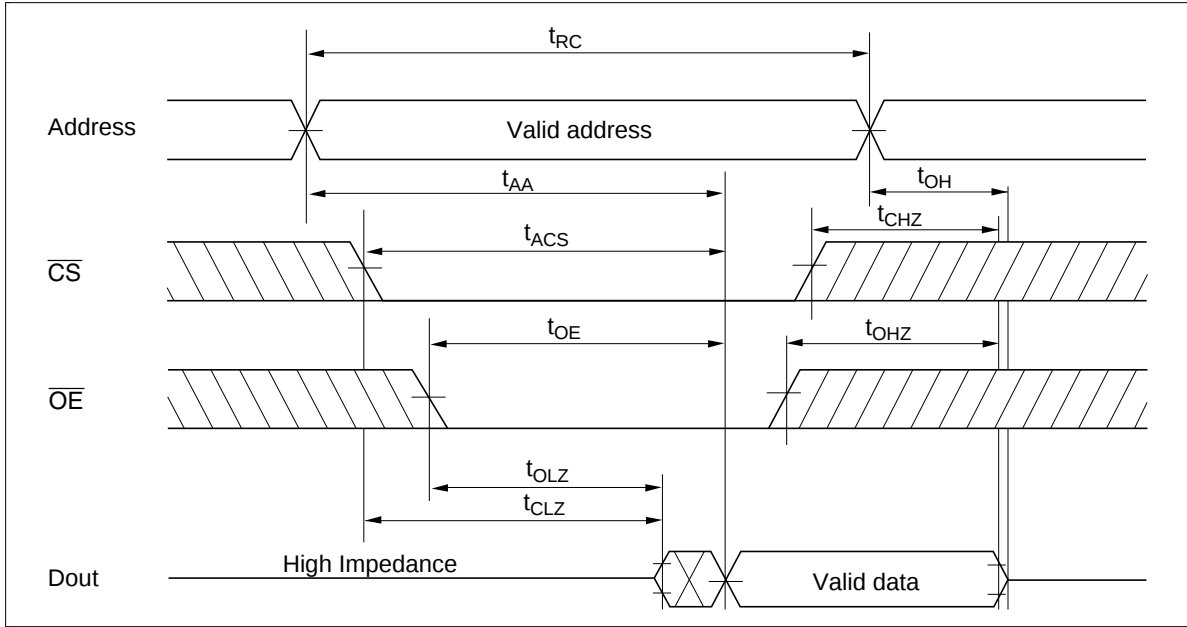
		HM621400H							
Parameter	Symbol	-10		-12		-15		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Write cycle time	t _{WC}	10	—	12	—	15	—	ns	
Address valid to end of write	t _{AW}	7	—	8	—	10	—	ns	
Chip select to end of write	t _{CW}	7	—	8	—	10	—	ns	9
Write pulse width	t _{WP}	7	—	8	—	10	—	ns	8
Address setup time	t _{AS}	0	—	0	—	0	—	ns	6
Write recovery time	t _{WR}	0	—	0	—	0	—	ns	7
Data to write time overlap	t _{DW}	5	—	6	—	7	—	ns	
Data hold from write time	t _{DH}	0	—	0	—	0	—	ns	
Write disable to output in low-Z	t _{OW}	3	—	3	—	3	—	ns	1
Output disable to output in high-Z	t _{OHZ}	—	5	—	6	—	7	ns	1
Write enable to output in high-Z	t _{WHZ}	—	5	—	6	—	7	ns	1

- Note:
1. Transition is measured ± 200 mV from steady voltage with Load (B). This parameter is sampled and not 100% tested.
 2. Address should be valid prior to or coincident with $\overline{CS}$ transition low.
 3. $\overline{WE}$ and/or $\overline{CS}$ must be high during address transition time.
 4. If $\overline{CS}$ and $\overline{OE}$ are low during this period, Dout pins are in the output state. Then, the data input signals of opposite phase to the outputs must not be applied to them.
 5. If the $\overline{CS}$ low transition occurs simultaneously with the $\overline{WE}$ low transition or after the $\overline{WE}$ transition, output remains a high impedance state.
 6. t_{AS} is measured from the latest address transition to the later of $\overline{CS}$ or $\overline{WE}$ going low.
 7. t_{WR} is measured from the earlier of $\overline{CS}$ or $\overline{WE}$ going high to the first address transition.
 8. A write occurs during the overlap of a low $\overline{CS}$ and a low $\overline{WE}$. A write begins at the latest transition among $\overline{CS}$ going low and $\overline{WE}$ going low. A write ends at the earliest transition among $\overline{CS}$ going high and $\overline{WE}$ going high. t_{WP} is measured from the beginning of write to the end of write.
 9. t_{CW} is measured from the later of $\overline{CS}$ going low to the end of write.

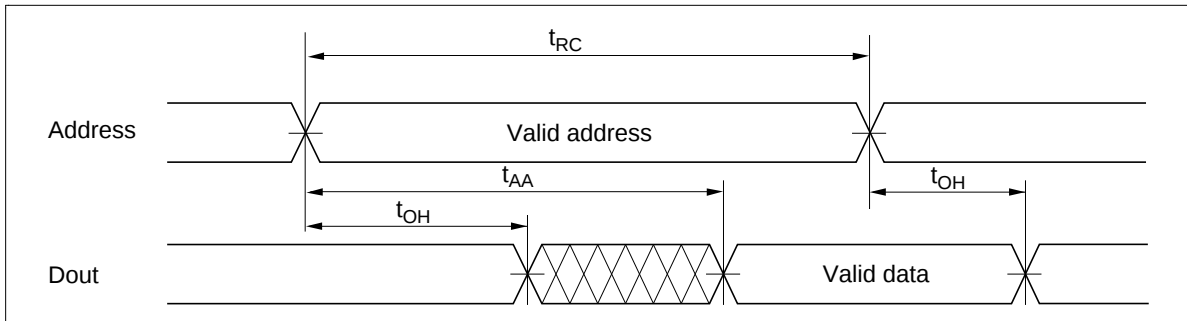
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Timing Waveforms

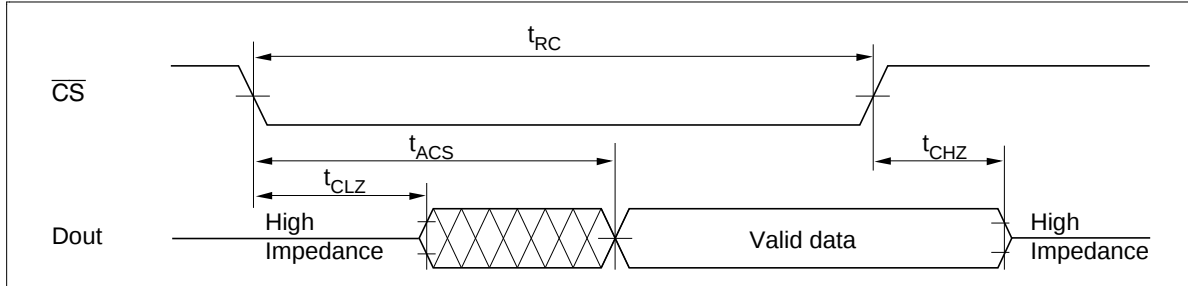
Read Timing Waveform (1) ($\overline{WE} = V_{IH}$)



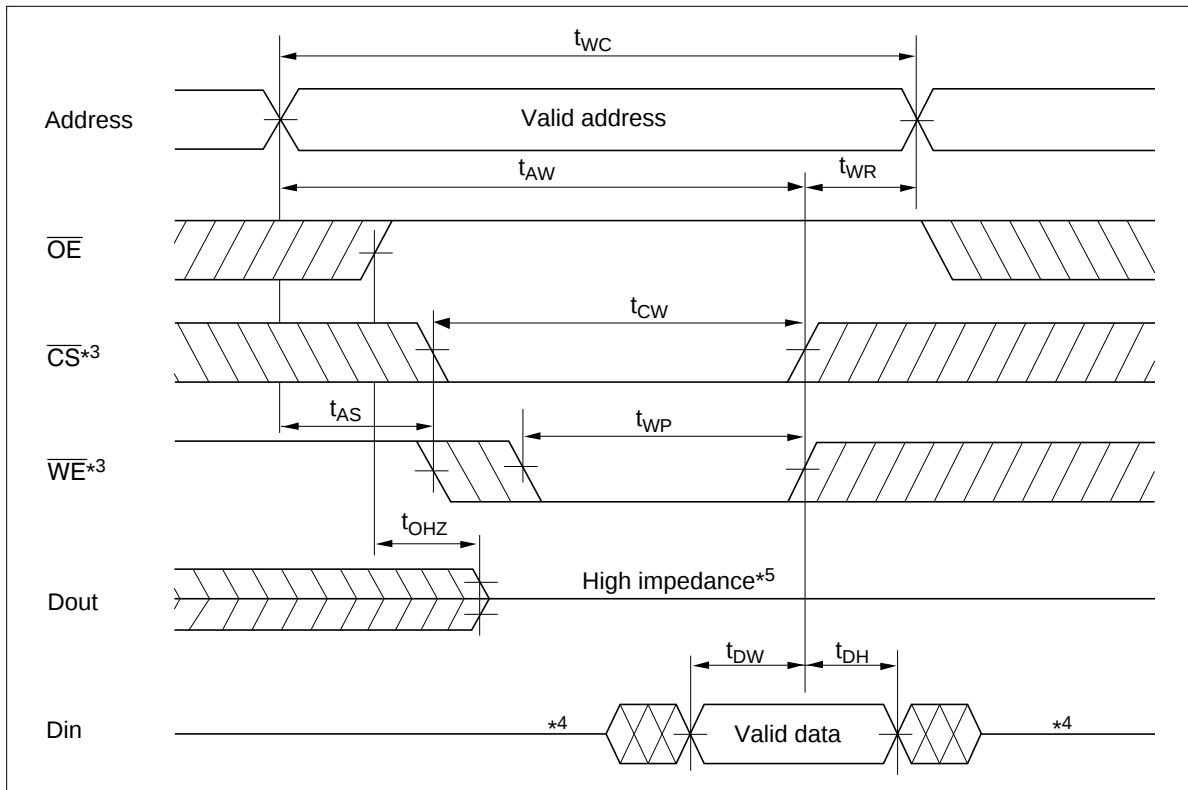
Read Timing Waveform (2) ($\overline{WE} = V_{IH}$, $\overline{CS} = V_{IL}$, $\overline{OE} = V_{IL}$)



Read Timing Waveform (3) ($\overline{WE} = V_{IH}$, $\overline{CS} = V_{IL}$, $\overline{OE} = V_{IL}$)*²

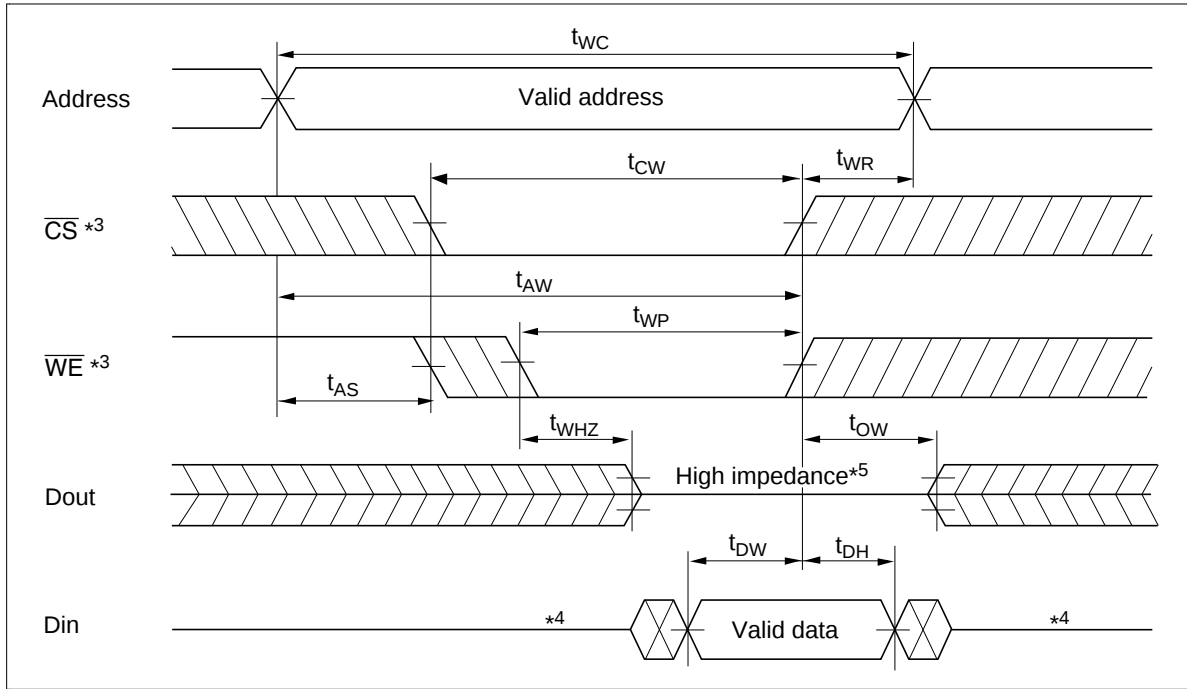


Write Timing Waveform (1) ($\overline{WE}$ Controlled)



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Write Timing Waveform (2) ($\overline{\text{CS}}$ Controlled)



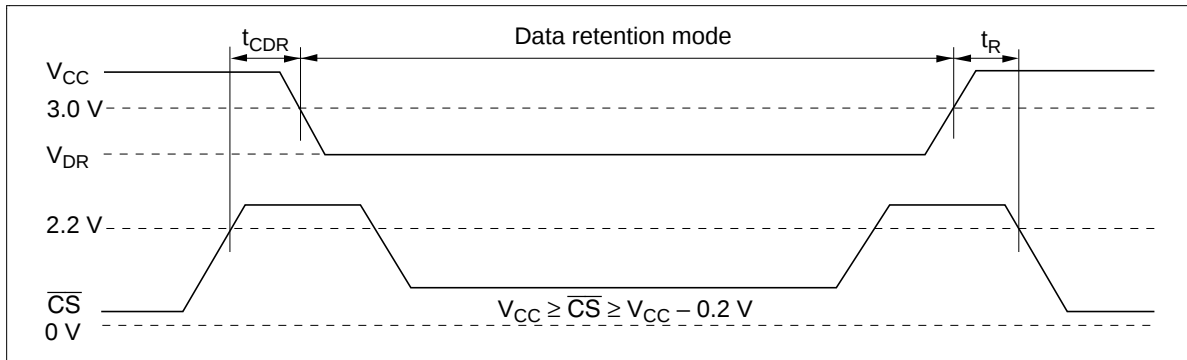
Low V_{CC} Data Retention Characteristics ($T_a = 0$ to $+70^\circ\text{C}$)

This characteristics is guaranteed only for L-version.

Parameter	Symbol	Min	Typ* ¹	Max	Unit	Test conditions
V_{CC} for data retention	V_{DR}	2.0	—	—	V	$V_{CC} \geq \overline{CS} \geq V_{CC} - 0.2 \text{ V}$ (1) $0 \text{ V} \leq V_{in} \leq 0.2 \text{ V}$ or (2) $V_{CC} \geq V_{in} \geq V_{CC} - 0.2 \text{ V}$
Data retention current	I_{CCDR}	—	50	800	μA	$V_{CC} = 3 \text{ V}, V_{CC} \geq \overline{CS} \geq V_{CC} - 0.2 \text{ V}$ (1) $0 \text{ V} \leq V_{in} \leq 0.2 \text{ V}$ or (2) $V_{CC} \geq V_{in} \geq V_{CC} - 0.2 \text{ V}$
Chip deselect to data retention time	t_{CDR}	0	—	—	ns	See retention waveform
Operation recovery time	t_R	5	—	—	ms	

Note: 1. Typical values are at $V_{CC} = 3.0 \text{ V}$, $T_a = +25^\circ\text{C}$, and not guaranteed.

Low V_{CC} Data Retention Timing Waveform

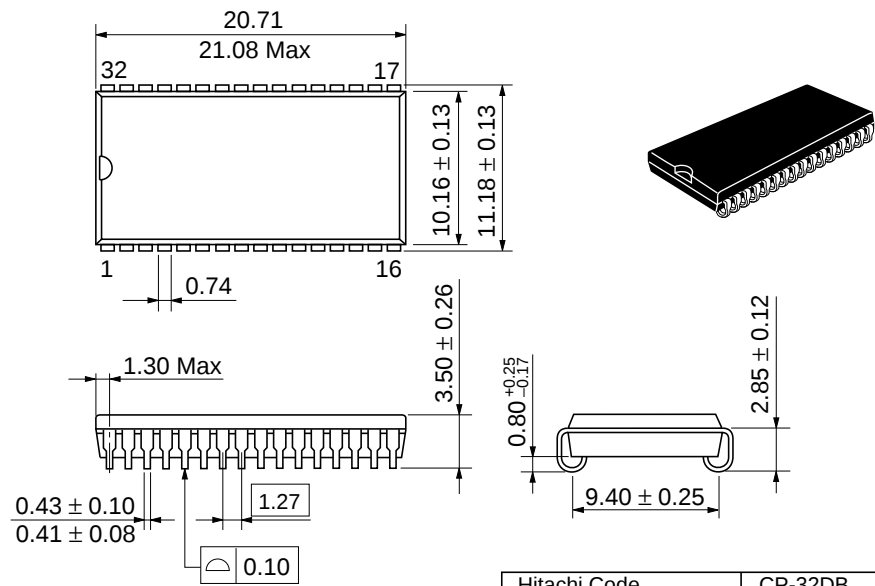


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Package Dimensions

HM621400HJP/HLJP Series (CP-32DB)

Unit: mm



Dimension including the plating thickness
Base material dimension

Hitachi Code	CP-32DB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.2 g

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HM621400H Series

Revision Record

Rev.	Date	Contents of Modification	Drawn by	Approved by
0.0	Jun. 4, 1997	Initial issue	Y. Saitoh	A. Ide
0.1	Nov. 20, 1997	Change of subtitle	K. Makuta	K. Makuta
0.2	Dec. 5, 1997	Features Addition of Operating current Addition of TTL standby current Addition of CMOS standby current Addition of Data retention current Addition of Data retention voltage Change of Block Diagram Operation table Title: I/O to Dout Dout: Din to High-Z Absolute Maximum Ratings P _r : 1.0/1.5 W to 1.0 W Change of notes Recommended DC Operating Conditions Change of notes DC Characteristics I _{CC} (max): 240/200/190 mA to 170/150/130 mA I _{SB} (max): 100/100/100 mA to 70/60/50 mA I _{SB1} (max): 10/1 mA to 5/1 mA Test conditions I _{CC} and I _{SB} : Addition of Min cycle Test conditions I _{SB1} : Addition of f = 0 MHz Capacitance Addition of C _{DIN} Input/output capacitance: C _{I/O} to C _{DOUT} AC Characteristics Change of Output load (A) t _{OE} , t _{CHZ} and t _{OHZ} (max): 5/6/8 ns to 5/6/7 ns t _{AW} , t _{CW} and t _{WP} (min): 6/8/10 ns to 7/8/10 ns t _{DW} (min): 5/6/8 ns to 5/6/7 ns t _{OHZ} and t _{WHZ} (max): 5/6/8 ns to 5/6/7 ns Note 4.: Correct error Low V _{CC} Data Retention Characteristics I _{CCDR} : —/2/300 μA to —/—/300 μA	T. Fukazawa	K. Makuta
0.3	May. 15, 1998	Features Change of Operating current Change of Block Diagram DC Characteristics I _{CC} (max): 170/150/130 mA to 200/180/160 mA	T. Fukazawa	K. Makuta

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Rev.	Date	Contents of Modification	Drawn by	Approved by
1.0	Sep. 15, 1998	Features Change of CMOS standby current (L-version) Change of Data retention current DC Characteristics I_{SB1} (max): 5/1 mA to 5/1.2 mA I_{SB1} (typ): —/— mA to 0.1/0.1 mA Low V_{CC} Data Retention Characteristics I_{CCDR} : —/—/300 μ A to —/50/800 μ A		
